



• General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

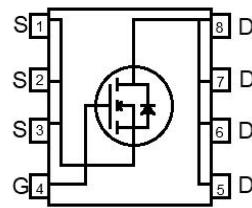
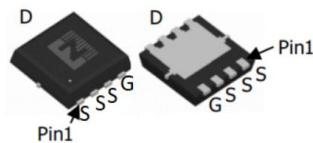
- BLDC Motor driver
- DC-DC
- Load switch

• Ordering Information:

Part NO.	ZMSA054N06M
Marking	054N06
Packing Information	REEL TAPE
Basic ordering unit (pcs)	5000

• Absolute Maximum Ratings ($T_c=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		60	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_c=25^\circ\text{C}$	45	A
	I_D	$T_c=75^\circ\text{C}$	45	A
	I_D	$T_c=100^\circ\text{C}$	43	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$;	180	A
Total Power Dissipation	P_D	$T_c=25^\circ\text{C}$	56	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	2.5	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	61	mJ
		$L=0.5\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	128	mJ
ESD Level (HBM)			CLASS 2	

 $V_{DS}= 60\text{V}$ $R_{DS(ON)} = 5.4\text{m}\Omega$ $I_D = 45\text{A}$ 



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R _{thJC}		-	2.7	°C/W
Thermal resistance, junction-ambient ^②	R _{thJA}		-	60	°C/W
Soldering temperature	T _{sold}		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	60			V
Gate Threshold Voltage	V _{GS(TH)}	V _{GS} =V _{DS} , I _D =250uA	1.3	1.8	2.5	V
Drain-Source Leakage Current	I _{DSS}	V _{GS} =0V, V _{DS} = 60V			1.0	uA
Gate- Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} = 0V			100	nA
Static Drain-source On Resistance	R _{DS(ON)}	V _{GS} =10V, I _D = 12A		5.4	7	mΩ
		V _{GS} =4.5V, I _D = 10A		7	8.5	mΩ
Forward Transconductance	g _{FS}	V _{DS} =5V, I _{SD} = 10A		16		s
Diode Forward Voltage	V _{FSD}	V _{GS} =0V, I _{SD} = 12A			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C _{iss}	f = 1MHz, V _{DS} =25V	-	1720	-	pF
Output capacitance	C _{oss}		-	960	-	
Reverse transfer capacitance	C _{rss}		-	91	-	
Gate Resistance	R _g	f = 1MHz	-	1.4		Ω
Total gate charge	Q _g	V _{DD} = 15V, I _D = 20A, V _{GS} = 10V	-	29	-	nC
	Q _g (4.5V)		-	14	-	
Gate - Source charge	Q _{gs}		-	4.4	-	
Gate - Drain charge	Q _{gd}		-	7.3	-	
Turn-ON Delay time	t _{D(on)}	V _{GS} =10V, V _{DS} =15V, R _G =3.3Ω, I _D =20A	-	16	-	ns
Turn-ON Rise time	t _r		-	17	-	ns
Turn-Off Delay time	t _{D(off)}		-	28	-	ns
Turn-Off Fall time	t _f		-	15	-	ns
Reverse Recovery Time	t _{RR}	V _{DD} =20V, dI _S /dt = 100A/us, I _S =20A	-	21	-	ns
Reverse Recovery Charge	Q _{RR}		-	20	-	nC



Fig.1 Gate-Charge Characteristics

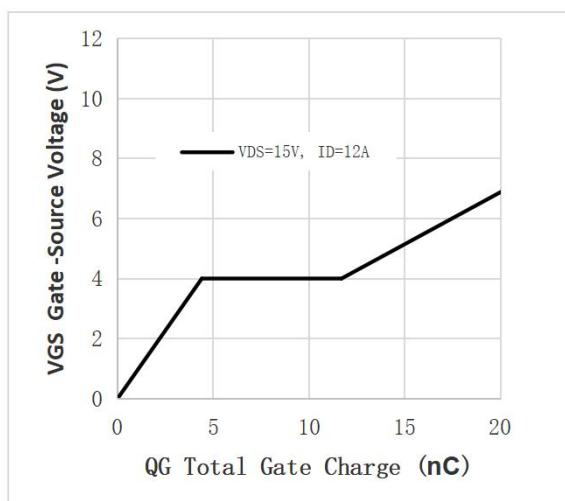


Fig.3 Power Dissipation

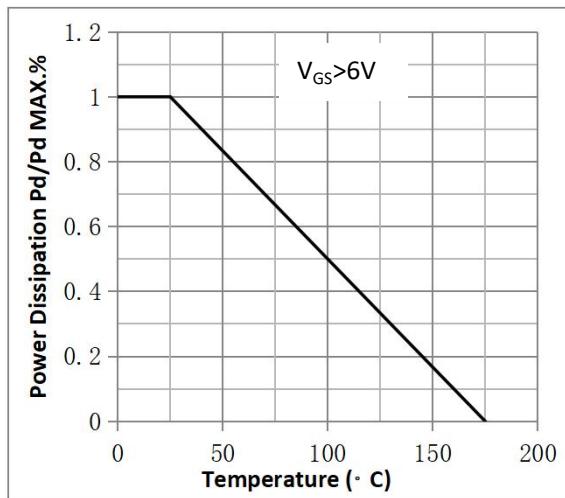


Fig.5 Threshold Voltage V.S Junction Temperature

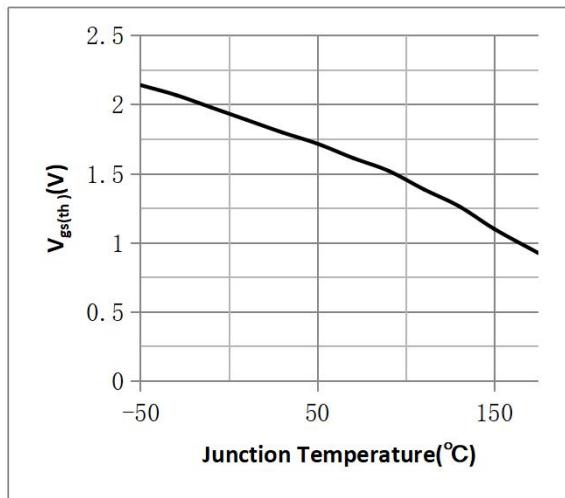


Fig.2 Capacitance Characteristics

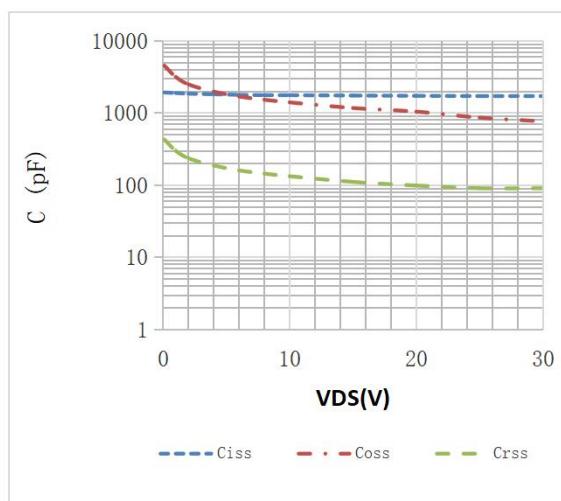


Fig.4 Typical output Characteristics

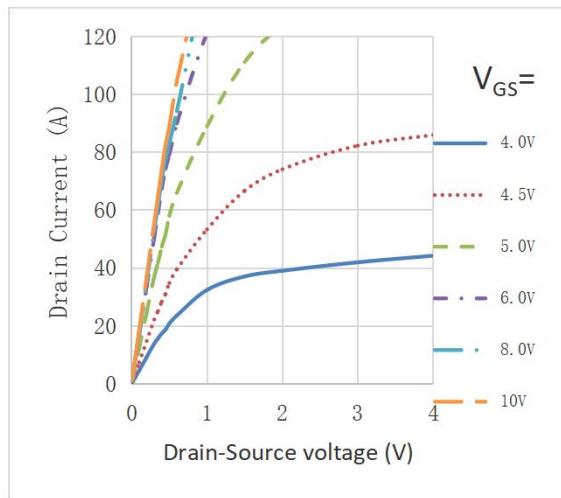


Fig.6 Resistance V.S Drain Current

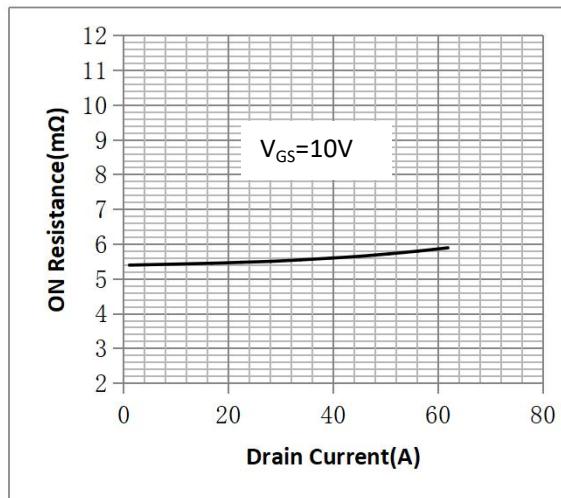




Fig.7 On-Resistance VS Gate Source Voltage

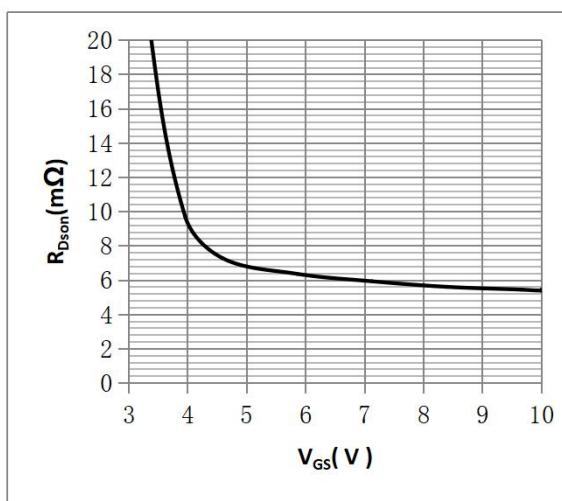


Fig.8 On-Resistance V.S Junction Temperature

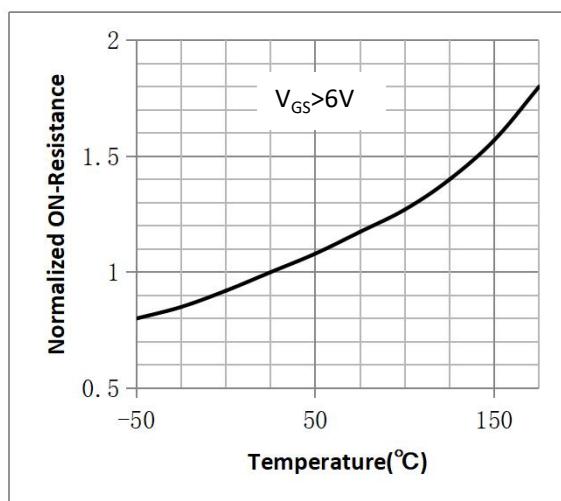


Figure 9. Diode Forward Voltage vs. Current

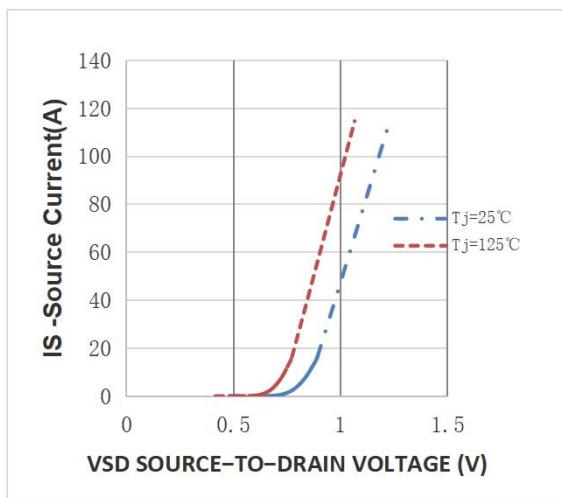


Figure 10. Transfer Characteristics

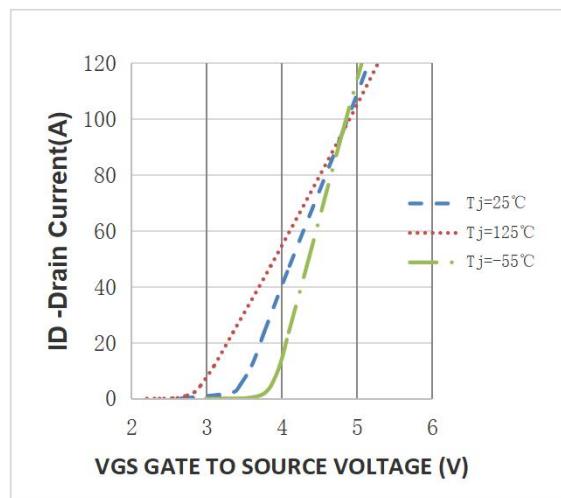
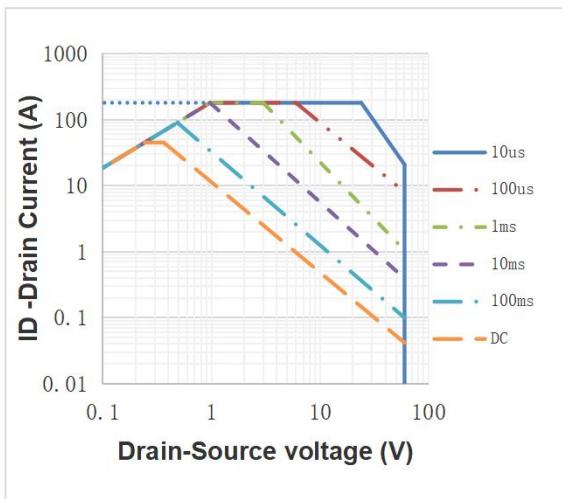
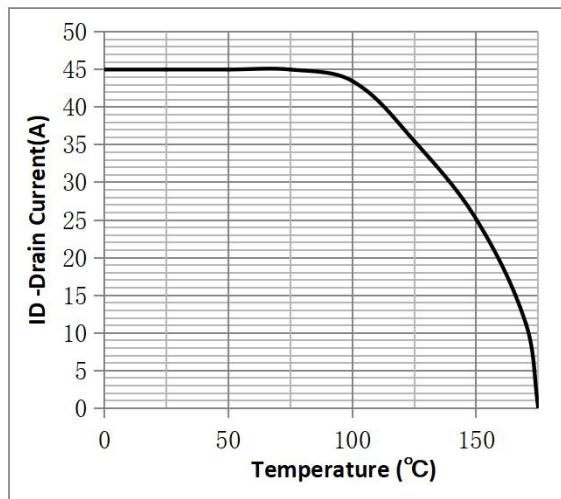


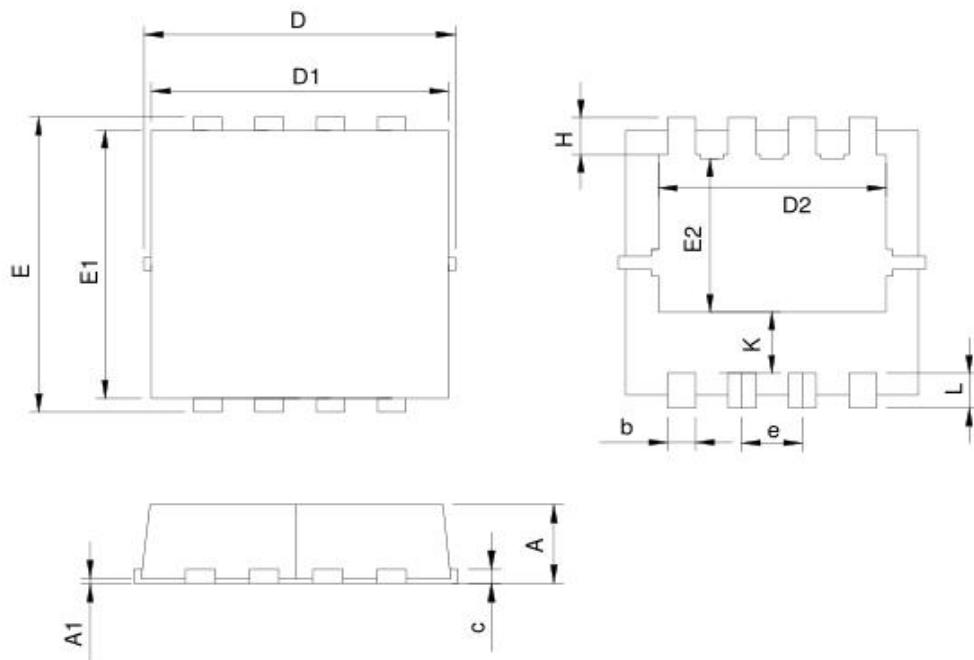
Fig.11 Safe Operating Area

Fig.12 ID vs. Junction Temperature^③

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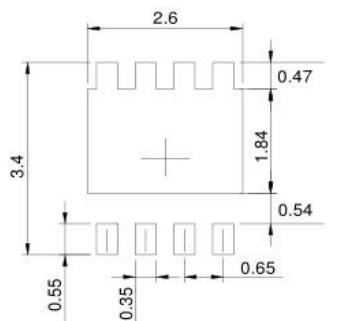


•DFN3*3 Package Outline



SYMBOL	DFN3.3x3.3-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	1.00	0.028	0.039
A1	0.00	0.05	0.000	0.002
b	0.25	0.35	0.010	0.014
c	0.14	0.20	0.006	0.008
D	3.10	3.50	0.122	0.138
D1	3.05	3.25	0.120	0.128
D2	2.35	2.55	0.093	0.100
E	3.10	3.50	0.122	0.138
E1	2.90	3.10	0.114	0.122
E2	1.64	1.84	0.065	0.072
e	0.65 BSC		0.026 BSC	
H	0.32	0.52	0.013	0.020
K	0.59	0.79	0.023	0.031
L	0.25	0.55	0.010	0.022

RECOMMENDED LAND PATTERN



UNIT: mm

**Note:**

- ① Pulse : VGS=+20V/-20V, Duty cycle=50%, Tj=175 °C, t=1000 hours; For DC , the following test conditions can be passed: VGS=+20V/-10V, Tj=175 °C, t=1000 hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. VGS=10V.

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Revision History

Version	Date	Change
A	2021.9.10	
B	2022.9.7	1.Add Reach, HF figure